REMARKS

The specification has been amended to correct errors of a typographical and grammatical nature. Due to the number of corrections thereto, applicants submit herewith a Substitute Specification, along with a marked-up copy of the original specification for the Examiner's convenience. The substitute specification includes the changes as shown in the marked-up copy and includes no new matter. Therefore, entry of the Substitute Specification is respectfully requested.

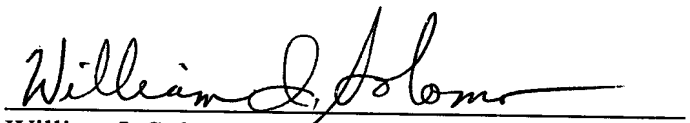
The abstract has also been amended to more clearly describe the features of the present invention.

Entry of the preliminary amendments and examination of the application is respectfully requested.

To the extent necessary, applicant's petition for an extension of time under 37 CFR 1.136. Please charge any shortage in the fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account No. 01-2135 (Case: 503.39144X00) and please credit any excess fees to such deposit account.

Respectfully submitted,

ANTONELLI, TERRY, STOUT & KRAUS, LLP



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IN THE TITLE:

Electroless Copper Plating Machine ~~Thereof~~, And Multi-Layer Printed Wiring Board

ABSTRACT OF THE DISCLOSURE

~~The main purpose of the present invention is to provide a~~ A method ~~of~~ is provided for removing plating blocking ions, such as anions, in pairs with copper ions and oxidant ions of ~~the~~ a copper ion reducing agent from ~~the~~ an electroless copper plating solution and keeping a constant salt concentration in the electroless copper plating solution during plating~~, a device to realize said method, and applications thereof~~. ~~For An~~ The electroless copper plating method~~, a device thereof, and application thereof, using~~ uses a plating solution containing copper sulfate as copper ion sources, and a copper ion complexing agent as copper ion sources, glyoxylic acid as a copper ion reducing agent, and a pH conditioner~~, the present invention~~. The method is characterized by precipitating and removing sulfuric and oxalic ions in said electroless copper plating solution and keeping an optimum concentration of at least one of sulfuric and oxalic ions in said electroless copper plating solution during plating.